

IN THE CLAIMS:

1-11. (Canceled)

12. (Previously Presented) A method of forming metal electrode pointed tips of a thermoelectric device, the method comprising:

forming a mask of patterned photoresist onto a layer of metal;
etching the layer of metal in the presence of the photoresist mask to produce substantially pointed tipped structures of metal; and
removing the photoresist.

13. (Original) The method as recited in claim 12, wherein the patterned photoresist forms an array of photoresist areas that correspond to areas for which tips of the substantially pointed tipped structures of metal are desired.

14. (Original) The method as recited in claim 12, wherein the metal is copper.

15. (Original) The method as recited in claim 12, further comprising:
coating the substantially pointed tipped structures of metal with a layer of a second metal.

16. (Original) The method as recited in claim 12, further comprising:
coating the substantially pointed tipped structures of metal with a layer of thermoelectric material.

17. (Original) The method as recited in claim 15, further comprising:
coating the layer of second metal with a layer of thermoelectric material.

18. (Original) The method as recited in claim 12, wherein the substantially pointed tipped structures are conical shaped.
19. (Original) The method as recited in claim 12, wherein the substantially pointed tipped structures are pyramid shaped.
20. (Currently Amended) A system of forming metal electrode pointed tips of a thermoelectric device, the system comprising:
means for forming a mask of patterned photoresist onto a layer of metal;
means for etching the layer of metal in the presence of the photoresist mask to produce substantially pointed tipped structures of metal; ~~and~~
means for removing the photoresist; and
means for coating the substantially pointed tipped structures of metal with a layer of thermoelectric material.
21. (Original) The system as recited in claim 20, wherein the patterned photoresist forms an array of photoresist areas that correspond to areas for which tips of the substantially pointed tipped structures of metal are desired.
22. (Original) The system as recited in claim 20, wherein the metal is copper.
23. (Original) The system as recited in claim 20, further comprising:
means for coating the substantially pointed tipped structures of metal with a layer of a second metal.
24. (Cancelled)

25. (Original) The system as recited in claim 23, further comprising:
means for coating the layer of second metal with a layer of thermoelectric material.
26. (Original) The system as recited in claim 20, wherein the substantially pointed tipped structures conical shaped.
27. (Original) The system as recited in claim 20, wherein the substantially pointed tipped structures are pyramid shaped.